PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data		
1.1 Company STMicroelectronics International N.V		
1.2 PCI No.		MDG/17/10568
1.3 Title of PCI		New Tape Header finishing procedure for EEPROM in WLCSP (packed with EPE foam)
1.4 Product Category		EEPROM in WLCSP
1.5 Issue date		2017-11-21

2. PCI Team		
2.1 Contact supplier		
2.1.1 Name	ROBERTSON HEATHER	
2.1.2 Phone	+1 8475853058	
2.1.3 Email	heather.robertson@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Benoit RODRIGUES	
2.1.2 Marketing Manager	Hubert LEDUC	
2.1.3 Quality Manager	Rita PAVANO	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	Process flow chart: Revision change in Process/Recipe like addition, deletion of process step (process technology, sawing, die attach, plasma, marking, packing, labelling, transportation, etc)	STATSChipPAC subcontractor

4. Description of change			
	Old	New	
4.1 Description	removing (at customer unreeling step) the protective belt could induce tension to the		
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact		

5. Reason / motivation for change	
5.1 Motivation	Reduction of potential tight winding of the tape.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change		
6.1 Description	N/A	

7. Timing / schedule	
7.1 Date of qualification results	2017-11-20
7.2 Intended start of delivery	2017-12-11
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation	
8.1 Description	

9. Attachments (additional documentations)

10568 Public product.pdf 10568 PCI End of Tape WLCSP ALL CUSTOMERS WITH EPE -1-.pdf

10. Affected parts		
	10. 1 Current	10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M24128-DFCS6TP/K	
	M24128S-FCU6T/T	
	M24256-DFCS6TP/K	
	M24512-DFCS6TP/K	
	M24C16-DFCU6TP/K	
	M24C32S-FCU6T/T	
	M24C64-DFCT6TP/K	
	M24C64-FCS6TP/K	
	M24C64S-FCU6T/T	
	M24M01-DFCS6TP/K	
	M24M02-DRCS6TP/K	
	M95128-DFCS6TP/K	
	M95256-DFCS6TP/K	
	M95512-DFCS6TP/K	
	M95M01-DFCS6TP/K	
	M95M02-DRCS6TP/K	



Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCI Title : New Tape Header finishing procedure for EEPROM in WLCSP (packed with EPE foam) *PCI Reference :* MDG/17/10568

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

M24C64-DFCT6TP/K	M95128-DFCS6TP/K	M24C32S-FCU6T/T
M24C64S-FCU6T/TF	M95M02-DRCS6TP/K	M24M01-DFCS6TP/K
M24512-DFCS6TP/K	M24C16-DFCU6TP/K	M24256-DFCS6TP/K
M24M02-DRCS6TP/K	M24128S-FCU6T/T	M95M01-DFCS6TP/K
M24128S-FCU6T/TF	M95512-DFCS6TP/K	M24C64-FCS6TP/K
M95256-DFCS6TP/K	M24C32S-FCU6T/TF	M24128-DFCS6TP/K
M24C64S-FCU6T/T		

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